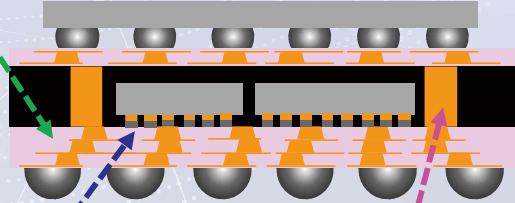


Thick Layer Photoresist For Plating

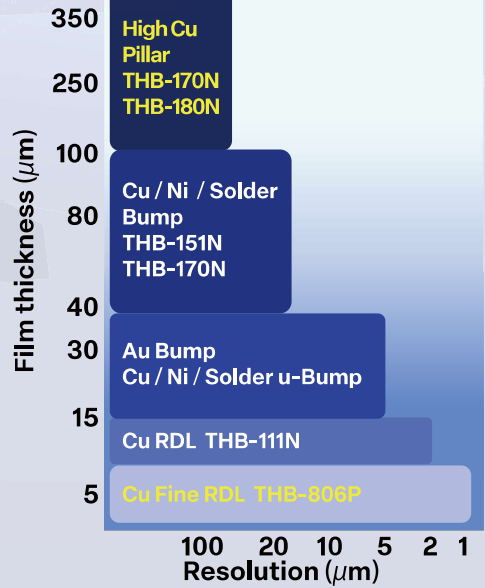
RDL □ Fine RDL
 FT : 5~15 μm
 Plating □ Cu



C4 / μ-Bump
 FT : 20~100 μm
 Plating : Cu / Ni / SnAg

High Cu pillar
 FT : >100 μm
 Plating : Cu

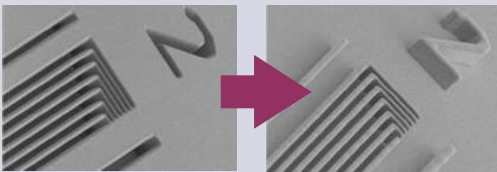
■ Product Line up



Cu RDL

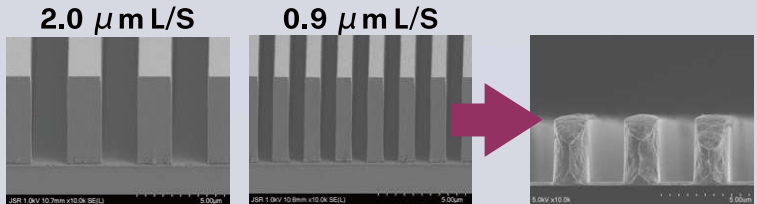
Cu Fine RDL

Negative Tone



Cu Plate
 THB stripped

Positive Tone

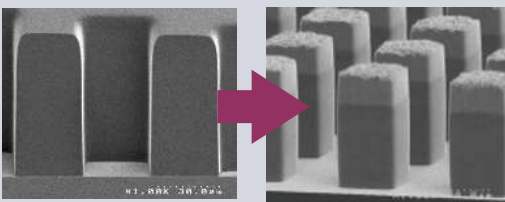


Film Thickness : 5 μm

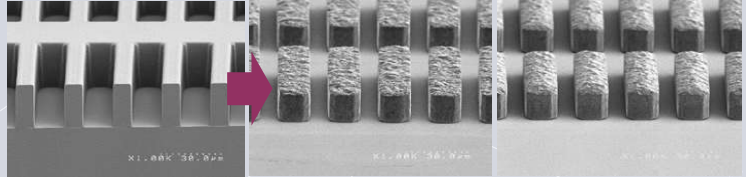
Cu Plate
 THB stripped

Cu / Ni / Solder Bump

Au Bump



Cu / Ni / SnAg Plate
 THB stripped



Cyanide Au Plate
 THB stripped

Non-cyanide Au Plate
 THB stripped

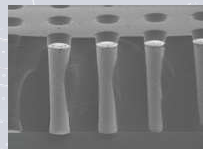
High Cu Pillar

20 μm φ



Film thickness : 170 μm

After Cu Plating



Cu height 190 μm / 50 μm φ

After Stripping

